

MKP Film Capacitor

Material Data Sheet

Product Class	Film Capacitor B2563x series PEC DC Link	
Date	18/11/2019	
IMDS ID if available	NA	
Version	5.02.1a (03/2019)	

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS** [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Heavy Metals	1C	Zinc	100	7440-66-6	3.0	
	Thermoplastic	2A	Polypropylene	100	9003-07-0	48.4	
	Thermoplastic	2A	PBT	70	26062-94-2	2.2	
	Mineral Materials	3A	Fiber Glass	30	65997-17-3		
Encapsulation	Duromer	2D	Polyurethane	100	67700-43-0	20.5	
	Thermoplastic	2A	PBT	70	26062-94-2	12.5	
	Mineral Materials	3A	Fiber Glass	30	65997-17-3		
Termination	Thermoplastic	2A	PBT	70	26062-94-2	9.2	
	Mineral Materials	3A	Fiber Glass	30	65997-17-3		
	Heavy Metals	1C	Brass(alloy) Pb	97 3	86376-49-0 7439-92-2	1.6	
	Heavy Metal	1C11	Copper	100	7440-50-8	1.7	
	Heavy Metal	1C8	Tin	100	7440-31-5	0.4	
	Thermoplastic	2A	Polyolefin	100	308070-21-5	0.5	
Sum in total:						100	

Sizes D x Ht [mm] weight range [kg] part numbers
 Ø85 x 54.5~89.5 0.37~0.49 B2563x

Not Part of a Product Class

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Important remarks:

- 1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated.
- 2) This Material Data Sheet contains typical values of the respective products set forth herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (valid not valid)

- no exemptions;
- Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;
- Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
- Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- Other Exemption than above